

# [ELECTRICAL PACKAGE AND MANUFACTURING METHOD THEREOF]

## Abstract

An electrical package and manufacturing method thereof is provided. A high stiffness, high electrical conductivity, low coefficient of thermal expansion and high thermal conductivity support substrate is used as an initial layer for building the package. A multi-layer interconnection structure is formed over the support substrate. Thereafter, a plurality of openings is formed over the support substrate. The openings expose a plurality of bonding pads on a bottom surface of the multi-layer interconnection structure. An electronic device is set up over the multi-layer interconnection structure. Contacts are formed inside the opening over the bonding pads.